

ABSTRACT OF THE DISCLOSURE

In a mounting structure of an optical module, an optical semiconductor device such as a light emitting device or a photo sensing device and an optical fiber are mounted. The optical fiber is directly mounted in a mounting groove formed on a top face of the substrate. The optical semiconductor device is mounted on a front face of a carrier corresponding to {110} surface or {100} surface equivalent to (110) surface or (100) surface of a single crystalline silicon. The carrier has a slanted first positioning face corresponding to {111} surface equivalent to (111) surface of the single crystalline silicon. The substrate has a slanted second positioning face corresponding to {111} surface equivalent to (111) surface of the single crystalline silicon with respect to the top face corresponding to {110} surface or {100} surface of the single crystalline silicon. Thus, the front face of the carrier becomes perpendicular to the top face of the substrate.